

A1

1. A temperature compensated attenuator device to compensate the effect of temperature changes in an electronic circuit comprising:

a low temperature co-fired ceramic-metal (LTCC-M) integrated package including a plurality of layers of thermistors and insulators, at least one of the thermistors comprising a sheet of thermistor material having a pair of major surfaces and a pair of electrodes formed on and laterally spaced apart by the major surfaces, the thermistor sheets layered with insulating layers and electrically connected to form the attenuator device.

Cancel claims 4-6.

~~79~~ (withdrawn)

Add claim ~~7~~ ¹⁰:

¹⁰ ~~7~~ The device of claim 6 wherein the insulating layer comprises a ceramic substrate formed from organic binder and glass.

Add claim ~~8~~ ¹¹:

¹¹ ~~8~~ The device of claim 1 wherein the attenuator comprises a circuit topology selected from the group consisting of pi filter, T filter, and bridged T filter.

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